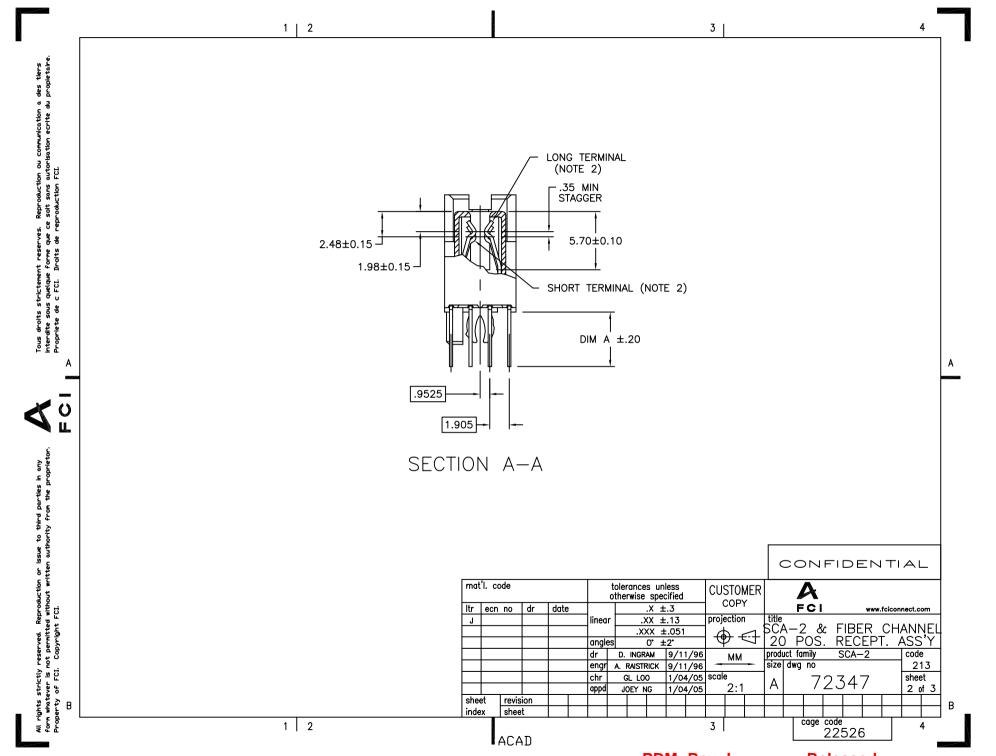


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REMAINING AREA.

1 | 2 3 PRODUCT PRODUCT POLARIZATION PRODUCT PRODUCT "A" DIM PI ATING RECOMMEDED P.C. BOARD THICKNESS PLATING PLATING. PI ATING NUMBER NUMBER NUMBER NUMBER PEG 72347-101 72347-001LF 72347-101LF 72347-001 2.79 YES 1.57mm (0.062") 72347-002 2.79 72347-102 72347-002LF 72347-102LF NO 72347-003 3.18 YES 72347-103 72347-003LF 72347-103LF NOTE (4) 2.36mm (0.093") NOTE (6) NOTE (8) NOTE (7) 3.18 72347-104 72347-004LF 72347-104LF 72347-004 NO 72347-005 4.06 72347-105 72347-005LF 72347-105LF YES 3.18mm (0.125") 4.06 72347-106 72347-006LF 72347-006 72347-106LF NO - NOTE 6 NOTE 8 - NOTE 7 -NOTES: 20.39 1) TRUE POSITION NOTES APPLY AT TERMINAL TIP. 2.19 ± 0.10 NOTE 5 CONTACTS IN POSITIONS 1 THRU 10 POSN 20 15 & 16 ARE SHORT TERMINALS. 2.60±0.10 DIA NOTE 5 CONTACTS IN POSITIONS 11, 12, 13, 14, AND 17, 18, 19, 20 ARE LONG TERMINALS. ø2.60±0.10 POSN 11 -RAW MATERIALS: 1.90 HOUSING: HTN, UL94V-O, COLOR: BLACK TYP CONTACTS: PHOSPHOR-BRONZE - 2.20±0.10 CONTACT PLATING: 30u" (0.76um) MIN. GXT PLATING OVER 50u" (1.27um) NICKLE MIN. UNDERPLATE IN CONTACT AREA. 100u" (2.54um) MIN. TIN-LEAD PLATING OVER 50u" (1.27um) MIN. 0 0 0 NOTE 5 Α 0 0 0 0 NICKLE UNDERPLATE IN P.C. BOARD LEG AREA. 50u" (1.27um) MIN. .95 0 0 NICKLE UNDERPLATE OVER REMAINING AREA. TYP. DIMENSIONS DO NOT APPLY TO CONNECTOR STYLES WITHOUT POLARIZATION PEG. (SEE CHART) 2.60±0.10 DIA. POSN 10 CONTACT PLATING: 30µ" (0.76µm) MIN. GOLD PLATING OVER 50µ" (1.27µm) NICKEL MIN. UNDERPLATE IN CONTACT AREA. 100µ" (2.54µm) MIN TIN-LEAD PLATING OVER 50µ" (1.27µm) MIN. NICKEL UNDERPLATE IN P.C. BOARD LEG AREA. 50µ" (1.27µm) MIN. _Y_ POSN 1 1.27 0.80±0.08 DIA NICKEL UNDERPLATE OVER REMAINING AREA. **♦** Ø0.05 **M** Y **M** TYP. 4.48 CONTACT PLATING: 30u" (0.76um) GOLD PLATING 20 PLC OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. 100u" (2.54um) - 200u"(5.08um) TIN PLATING OVER RECOMMENDED PC BOARD 50u" (1.27um) -100u" (2.54um) NICKEL UNDERPLATE IN MOUNTING DIMENSIONS P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER REMAINING AREA. COMPONENT SIDE CONFIDENTIAL CONTACT PLATING: 30u" (0.76um) GXT PLATING OVER 50u" (1.27um) NICKLE UNDERPLATE IN CONTACT AREA. mat'l. code 100u" (2.54um) - 200u"(5.08um) TIN PLATING OVER tolerances unless CUSTOMER otherwise specified 50u" (1.27um) -100u" (2.54um) NICKEL UNDERPLATE IN

THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM THICK CIRCUIT BOARD.

P.C. BOARD LEG AREA. 50u" (1.27um) NICKEL UNDERPLATE OVER

1 | 2

THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

COPY FCI Itr ecn no dr date .x ±.3 www.fciconnect.com .XX ±.13 projection linear SCA-2& FIBER CHANNEL .XXX ±.051 20 POS. RECEPT. ASS'Y angles 0° ±2° dr D. INGRAM 9/11/96 product family SCA-2 code MM A. RAISTRICK 9/11/96 size dwg no 213 engr 1/04/05 scale chr GL LOO sheet 72347 2:1 appd JOEY NG 1/04/05 3 of 3 sheet revision index sheet cage code 3 22526 **■**ACAD

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